ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INTERNATION	ial Composition I right 2005. IPC, Bannoo onal and Pan-American	<b>Declaration</b> Ekburn, Illinois. A copyright conver	ll rights reserved u utions.	nder both	This docume level parts, tl	ent is a declaration er	on of the substance acompasses all lo	es within the man wer level material	ufacturer liste s for which the	d item. Note: i e manufacturer	f the item is an as r has engineering	ssembly with low responsibility.	
759_91 1	1 IPC Web Site for Information on IPC-1752 Standard Form Typ			Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials and	als and Mfg Information			
upplier Information													
ompany name*	Company uni	Company unique ID			Unique ID Authority				Response Date*				
nsemi									2024-05-23				
Contact Name Tit			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA			Prod	Product-Env-Stewards@onsemi.com				
uthorized Representative*	Title - Repres	Title - Representative			Phone - Representative*			Emai	Email - Representative*				
roduct-Env-Stewards	Product Envi	Product Enviro Compliance			NA			Prod	Product-Env-Stewards@onsemi.com				
Requester Item Number		Mfr Item Number Mfr Item Name				Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	FGA2	FGA25N120ANTDTU NPTTIGBT T		D3PN 25A 1200V		2024-05-23		СРА		5434.65	mg	Each	
Ianufacturing Proccess	Information						-	-					
Terminal Plating / Grid Array Material Ter		Terminal Base A	minal Base Alloy J-STD-020 MSI		Rating	Peak Process Body Temperature Max		ture Max Time a	t Peak Tempe	erature Numb	per of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy	U Alloy NA			0 C 30		30	sec	seconds 3			
omments													
or more information regardi	ng material compositio	on please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	41.8	mg	Supplier	Silicon (Si)	7440-21-3		41.8	mg	
Die Attach	1.84	mg	Supplier	Silver (Ag)	7440-22-4		0.0276	mg	
			А	Lead (Pb)	7439-92-1	7a	1.7204	mg	
			Supplier	Tin (Sn)	7440-31-5		0.092	mg	
Lead Frame	3624.71	mg	Supplier	Tin (Sn)	7440-31-5		3.62	mg	
			Supplier	Copper (Cu)	7440-50-8		3620.0017	mg	
			Supplier	Phosphorus (P)	7723-14-0		1.088	mg	
Mold Compound-Black	1736.8	mg		Proprietary	proprietary data		86.84	mg	
			Supplier	Carbon Black (C)	1333-86-4		8.684	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		1293.916	mg	
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		260.52	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		86.84	mg	
Plating	26.5	mg	Supplier	Tin (Sn)	7440-31-5		26.5	mg	
Wire Bond - Al	3.0	mg	Supplier	Aluminum (Al)	7429-90-5		3	mg	

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3